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TECHNOLOGY CENTER 2800

**PATENT APPLICATION**  
**RESPONSE UNDER 37 CFR §1.116**  
**EXPEDITED PROCEDURE**  
**TECHNOLOGY CENTER ART UNIT 2811**

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Kazuo TANAKA

Group Art Unit: 2811

Application No.: 09/586,963

Examiner: C. Nguyen

Filed: June 5, 2000

Docket No.: 039894.01

For: A SEMICONDUCTOR DEVICE AND METHOD FOR MAKING THE SAME  
THAT PROVIDE ARRANGEMENT OF A CONNECTING REGION FOR AN  
EXTERNAL CONNECTING TERMINAL (AS AMENDED)

**AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116**

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

In reply to the Office Action dated January 23, 2002, please amend the above-  
identified application as follows:

**IN THE CLAIMS:**

Please replace claim 2 as follows:

2. (Four Times Amended) A semiconductor device including a bonding pad,  
wherein the bonding pad is a multiple wiring layer structure, the bonding pad comprising:  
a first conductive layer connected to a conductive member for external  
connection;  
a second conductive layer disposed below said first conductive layer, the  
second conductive layer having a plurality of openings;

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a third conductive layer disposed below said second conductive layer;  
a first insulating interlayer disposed between said first conductive layer and  
said second conductive layer;  
at least one first through hole provided in said first insulating interlayer;  
a fourth conductive layer filling said at least one first through hole;  
a second insulating interlayer disposed between said second conductive layer  
and said third conductive layer;  
at least one second through hole provided in said second insulating interlayer  
the said at least one first through hole disposed substantially directly above said at least one  
second through hole; and  
a fifth conductive layer filling said at least one second through hole, wherein  
said first insulating interlayer and said second insulating interlayer are connected to each  
other through said openings of said second conductive layer, and a contiguous section of said  
first insulating interlayer with said second insulating interlayer is, thereby, formed between  
said first conductive layer and said third conductive layer.

REMARKS

Claims 2-8, 12-14 and 21 are pending. By this Amendment, claim 2 is amended.

Entry of the amendments is proper under 37 C.F.R. §1.116 since the amendments: (a) place the application in condition for allowance for the reasons discussed herein; (b) do not raise any new issue requiring further search and/or consideration since the amendments merely amplify issues discussed throughout prosecution; (c) do not present any additional claims without canceling a corresponding number of finally rejected claims; and (d) place the application in better form for appeal, should an appeal be necessary. The amendments are necessary and were not earlier presented because they are made in response to arguments raised in the final rejection. Entry of the amendments is thus respectfully requested.